



॥ सा विद्या या विमुक्तये ॥

भारतीय प्रौद्योगिकी संस्थान धारवाड़

Indian Institute of Technology Dharwad

High Voltage Isolated Differential Probe

EE314: EDL Project Evaluation 2

Team Members:

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Project Supervisor

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Project Timeline

A. First Evaluation

1. Study of existing solutions
2. Requirement Building / Spec freeze
3. High-level system Design by 27/Jan 2023



B. Second Evaluation

4. Simulation
5. Prototyping
6. PCB design by 17/Feb 2023



C. Third Evaluation

7. Prototyping and Assembling
8. Integration 17/March 2023



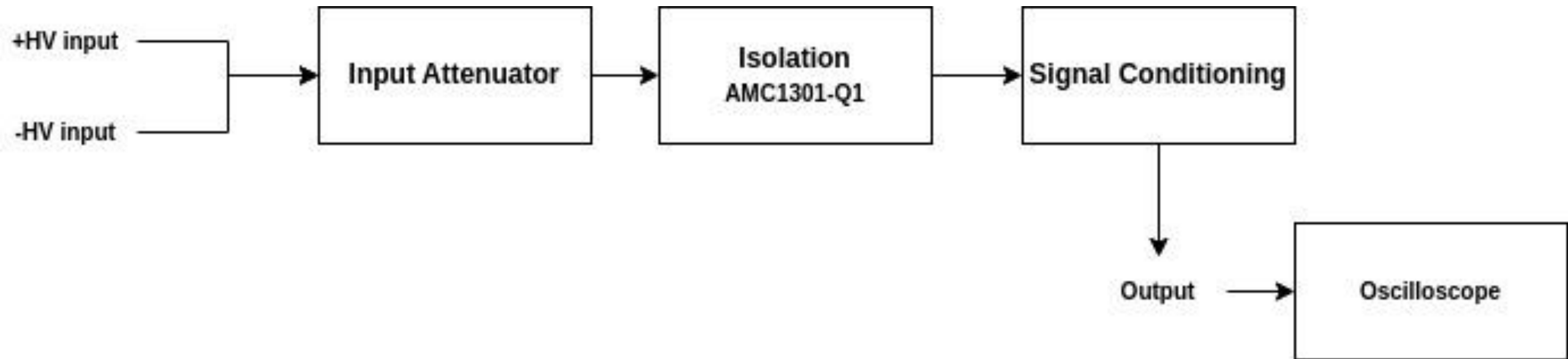
D. Final Evaluation

9. Testing and Calibration
10. Bugs and Fixing
11. Final PoC System Demonstration 10/April 2023

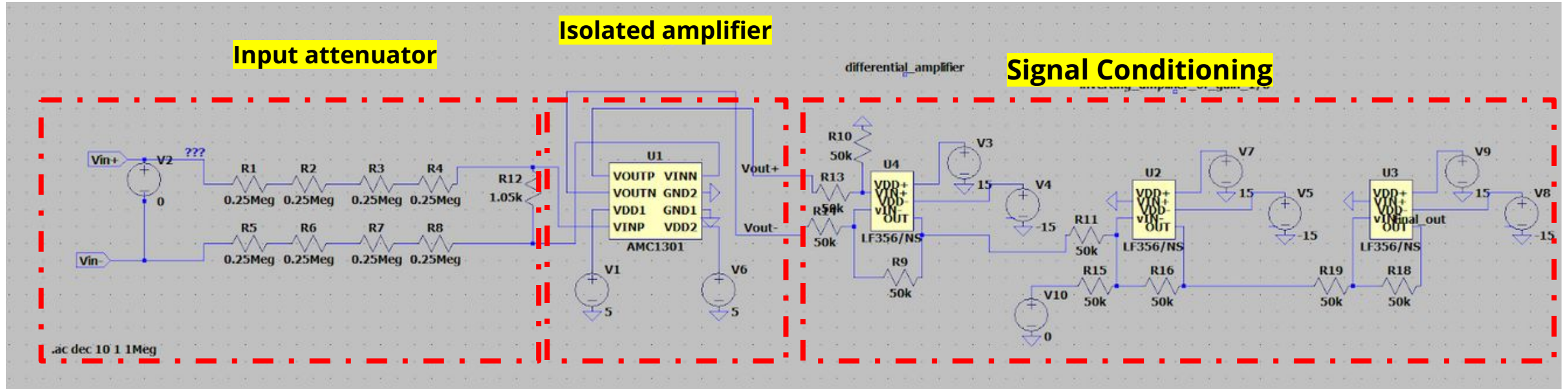
Wish specifications:

- Voltage Range: **0-600V**
- Impedance: **10M Ω**
- Bandwidth: **DC-5MHz**
- Common Mode Rejection Ratio (CMRR): **> 65dB**
- Signal Noise Ratio (SNR): **> 65dB**
- Isolation Voltage Rating: **1000V**
- Input Connector: **Banana jack type**
- Output Connector: **BNC**
- Operating Temperature: **10°C to 50°C**
- Power Source: **External**

System Block diagram



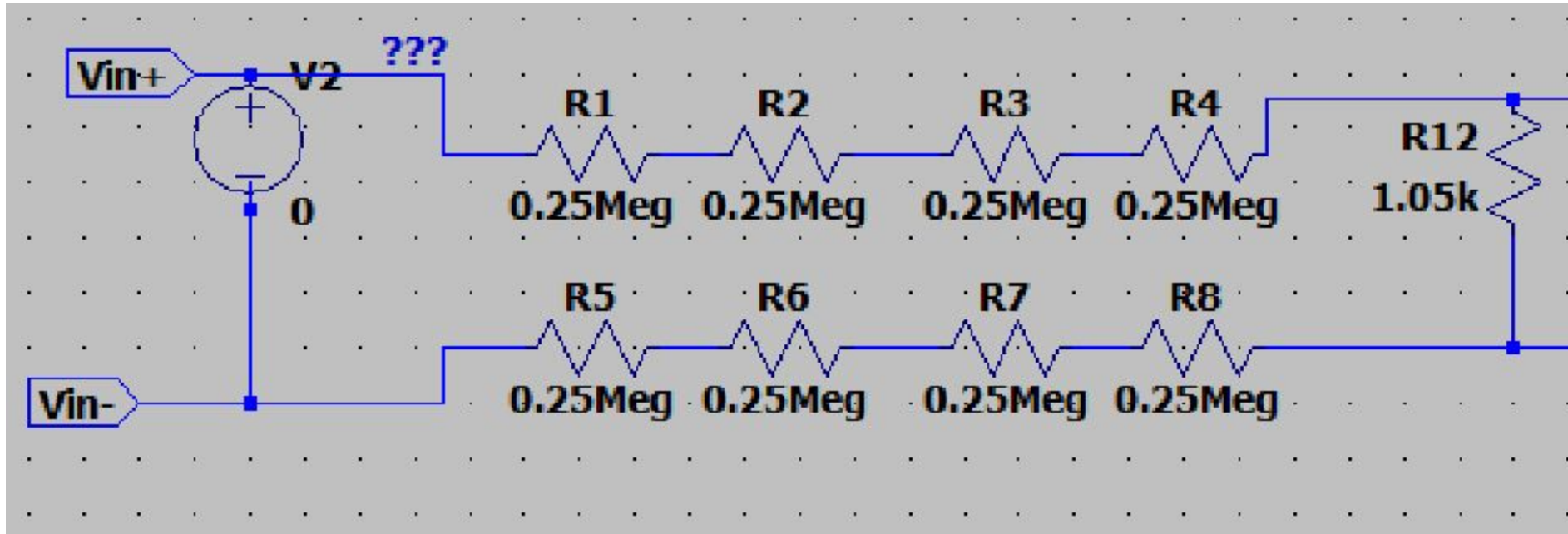
Circuit Schematic



Stages:

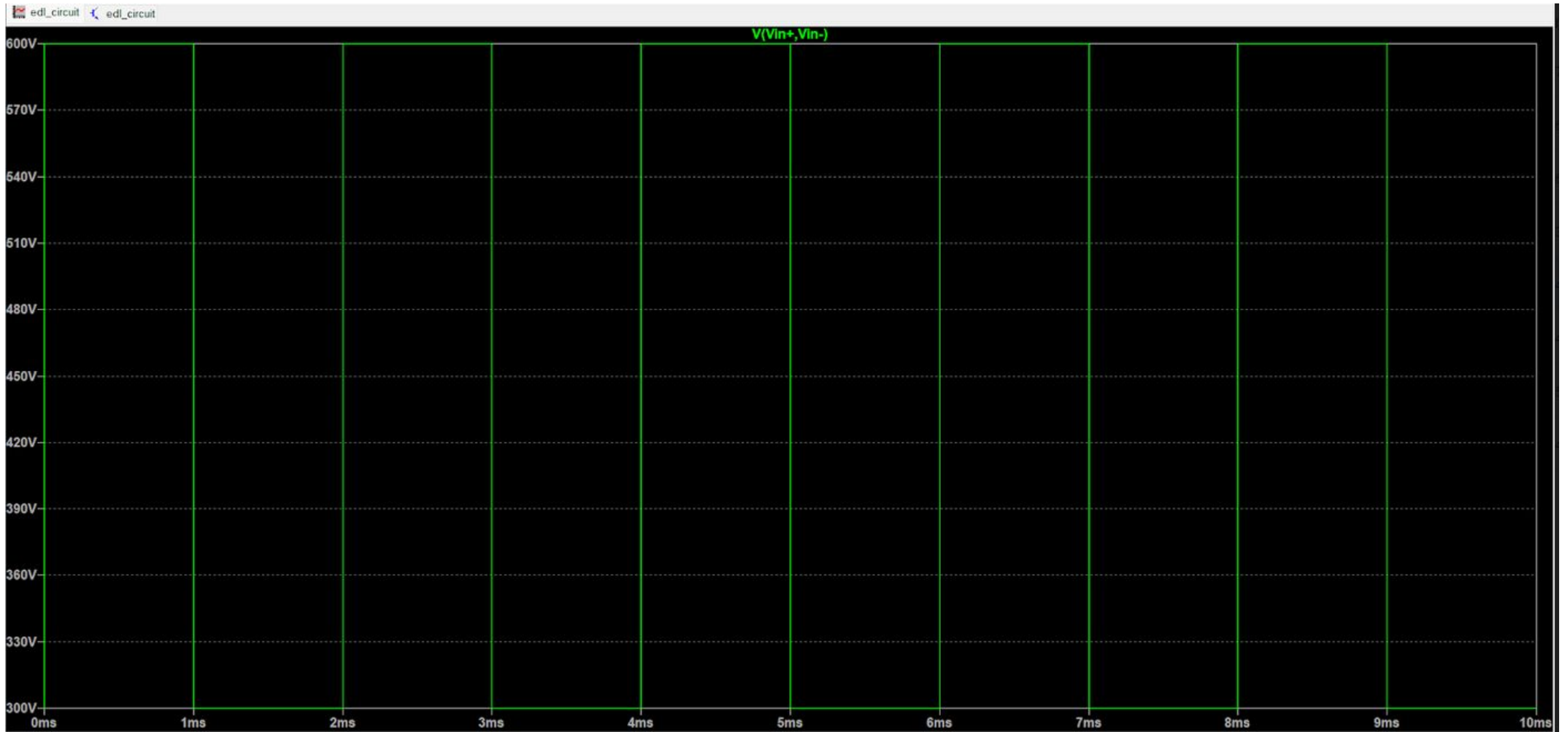
Input attenuator(voltage divider)(attenuation 1/2000)
isolation amplifier (AMC1301 IC) (bandwidth=1MHz)
differential amplifier
inverting amplifier (for gain correction)
inverting amplifier (for offset correction)

Input Attenuator Stage

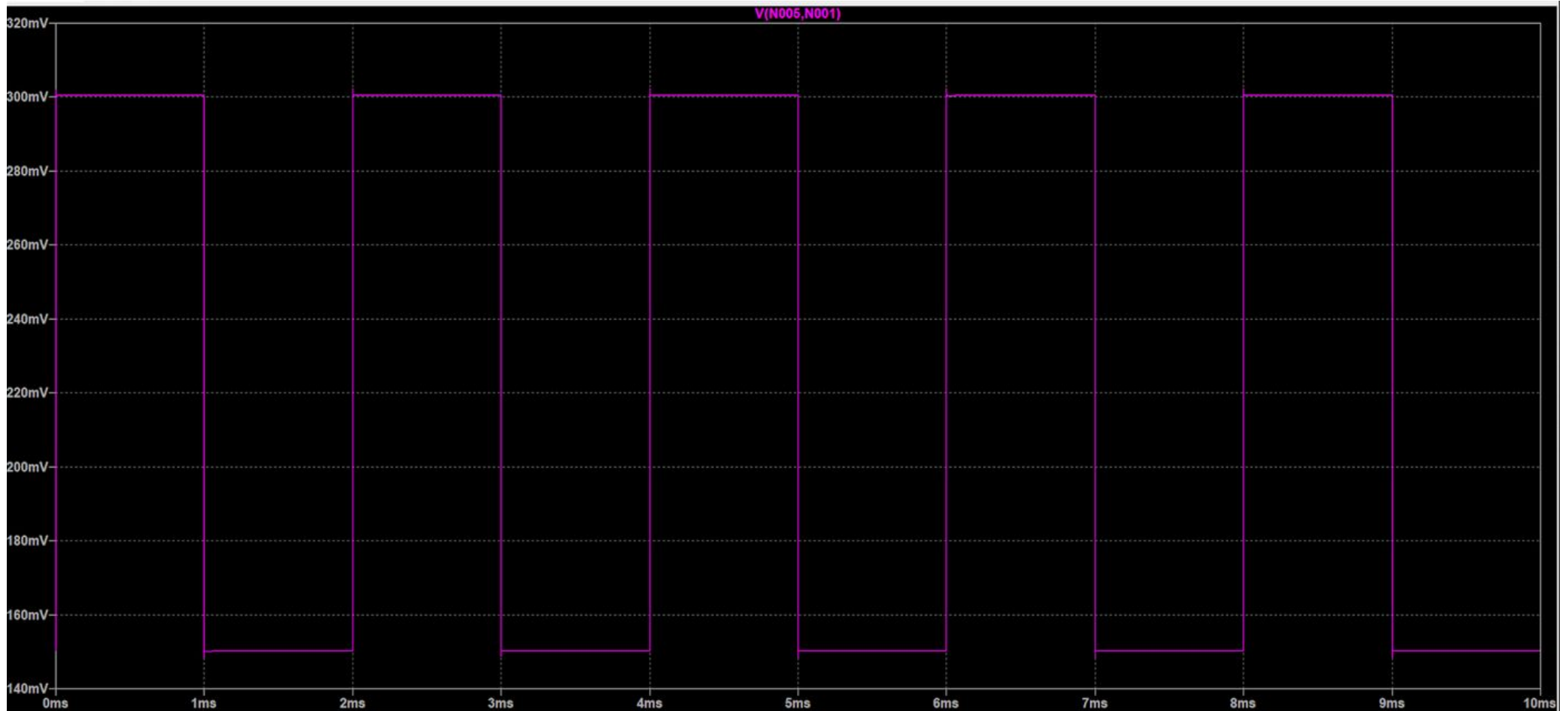


Attenuation: 1/2000

High voltage Input



Output after Attenuator



Isolated Amplifier Stage AMC1301

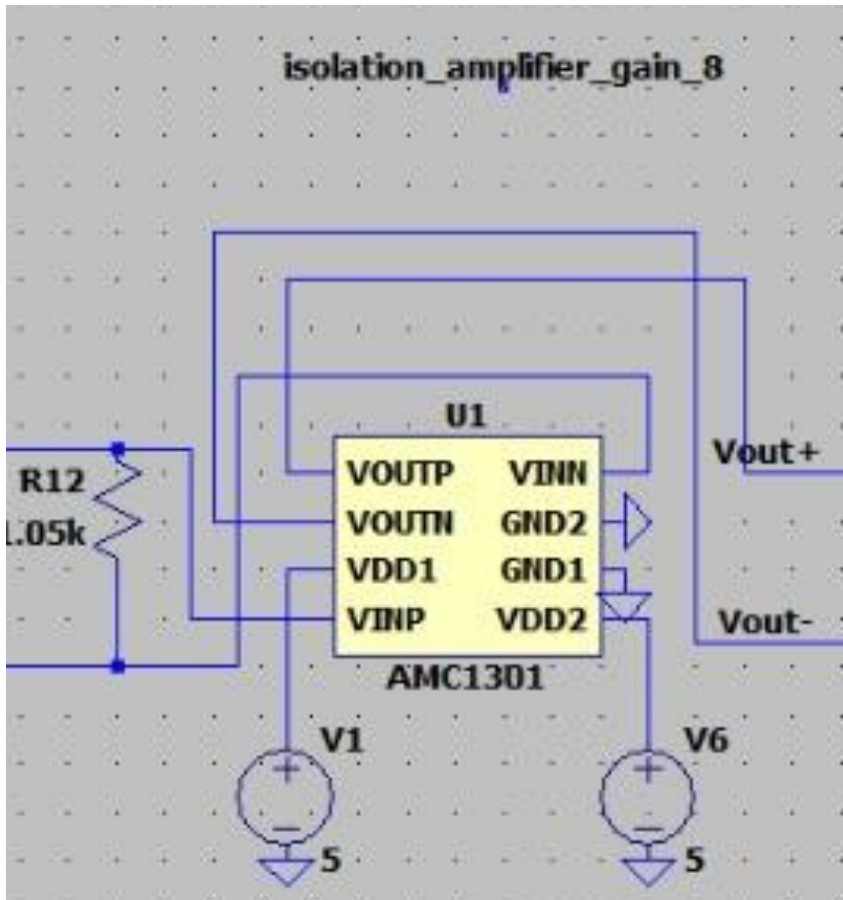


Bandwidth: 1MHz

gain: 8

Vdd: -0.3 to 7V

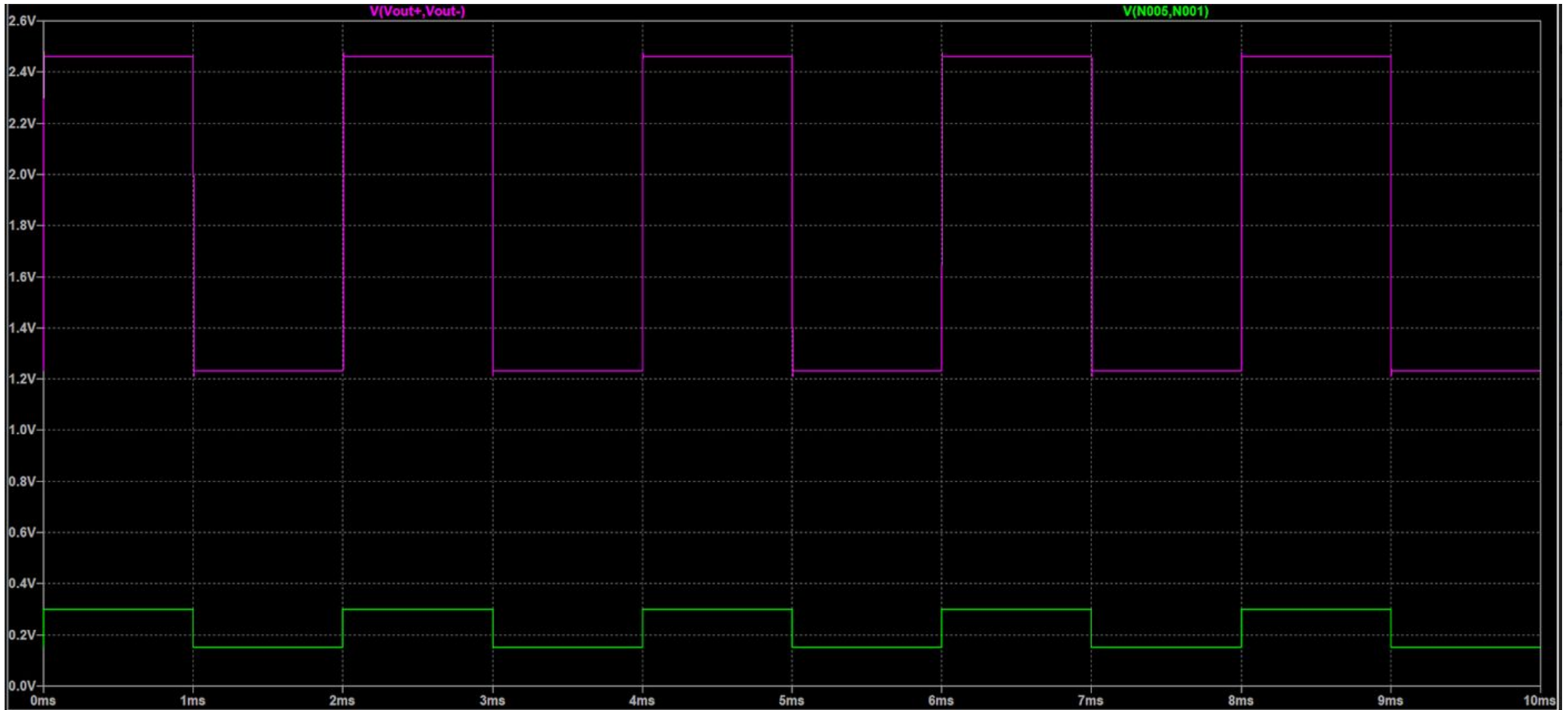
Input voltage range : 330mV (calculated by simulations)



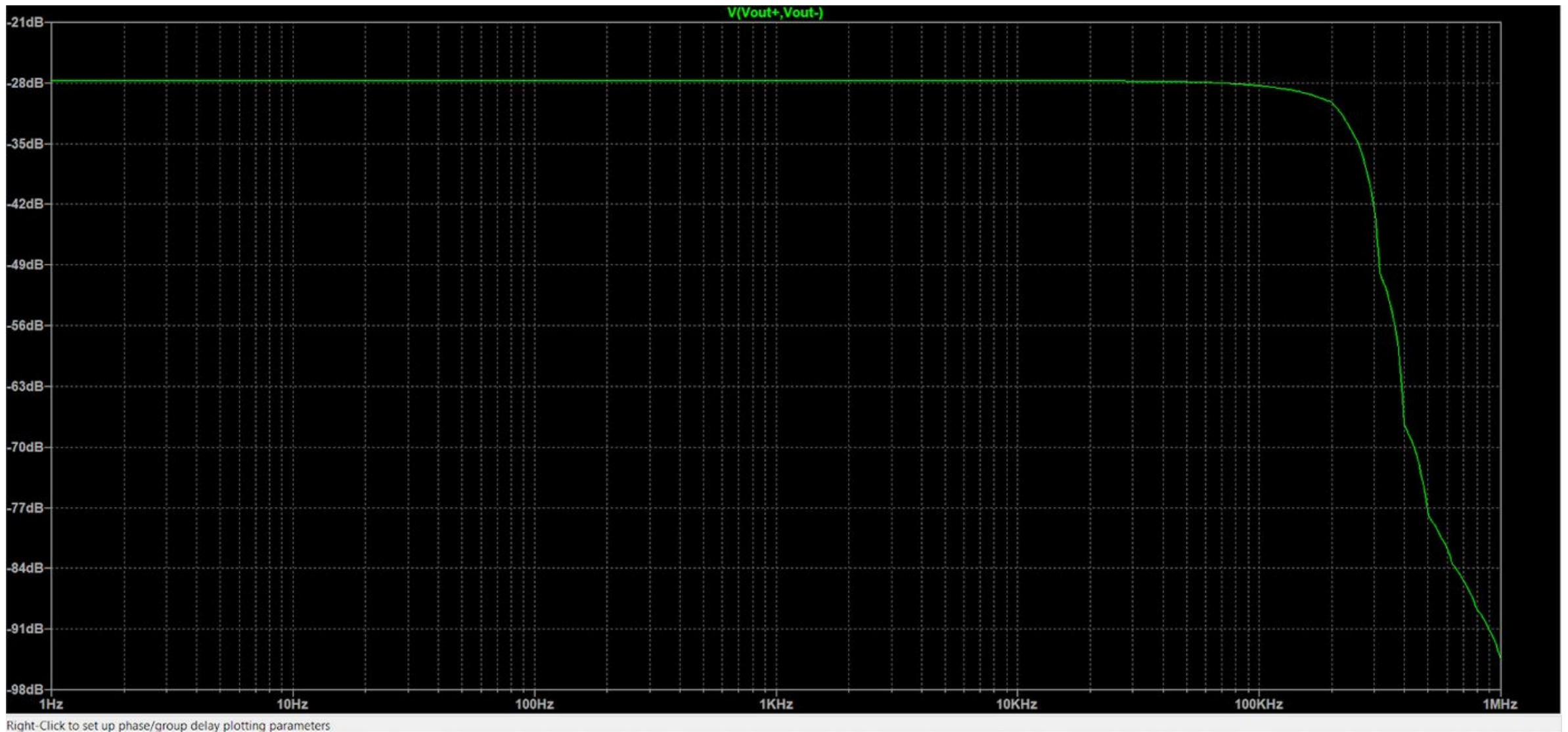
- **Specs**

GBWP	—1000 kHz
CMRR	— 92 dB
Operating Temperature	—(-40 to 125 c)
VDD	— (-0.3 to 7) V
Input Voltage Range	— (GND1 - 6) to (VDD+ 0.5)

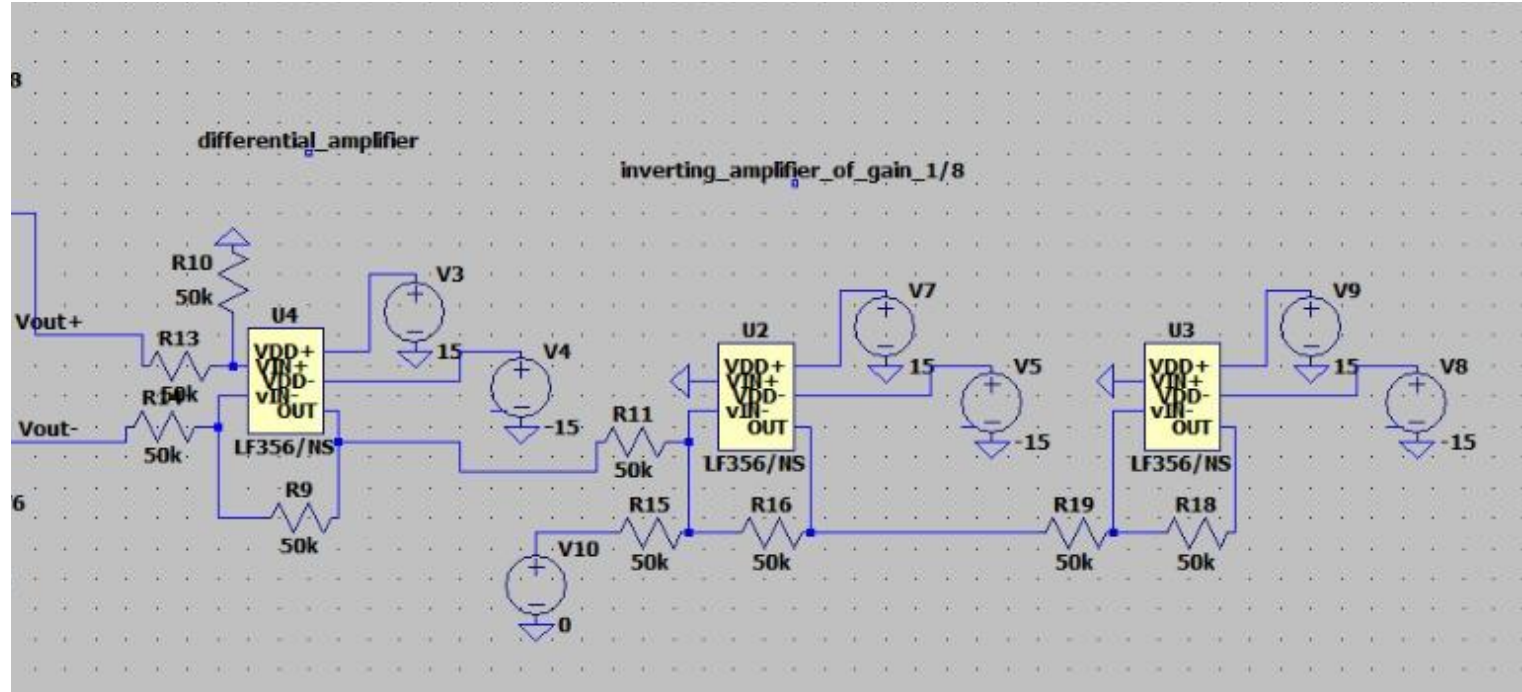
Input and Output of Isolation amplifier



AC analysis for Sinusoidal



Signal Conditioning

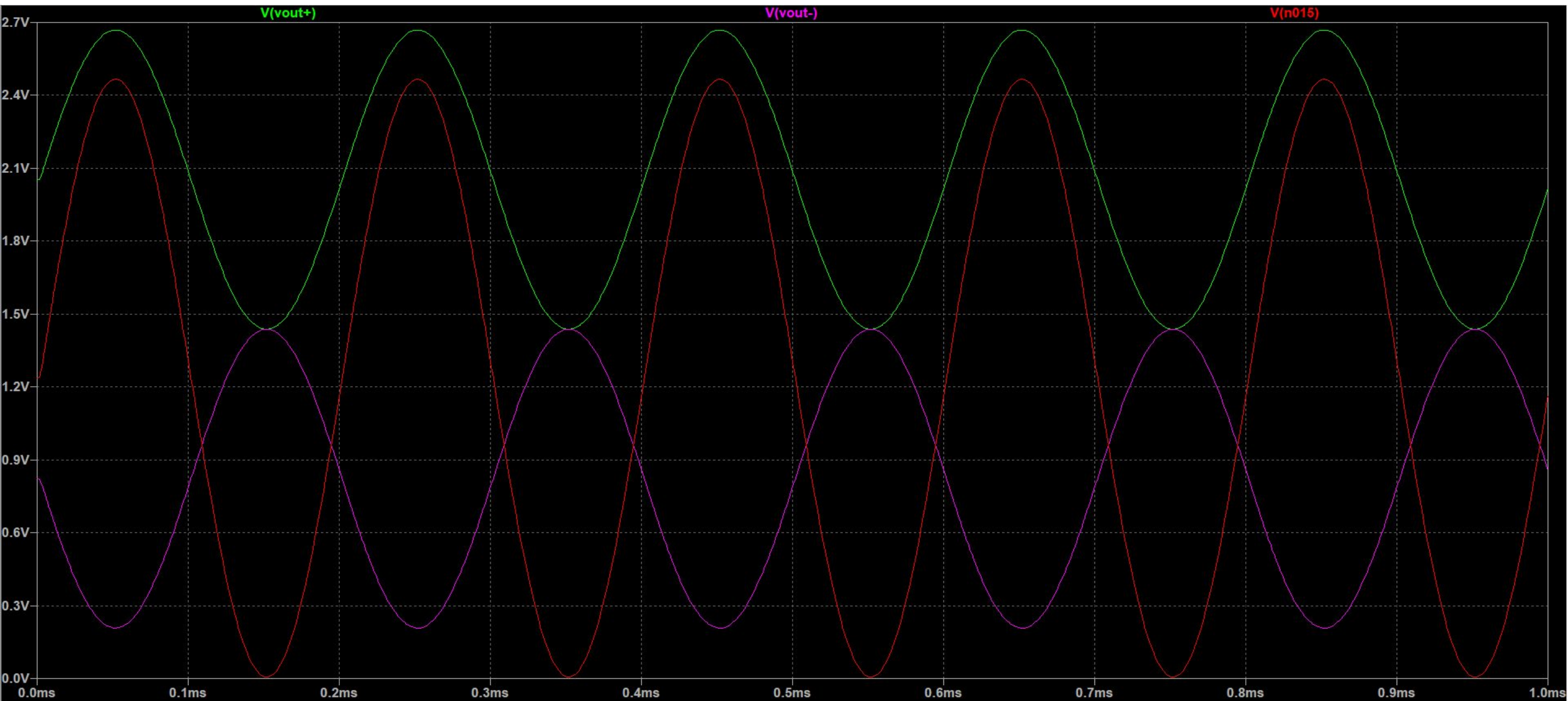


IC (LF356)

Differential amplifier : making output single ended

Inverting amplifier : used for trimming of gain and offset correction

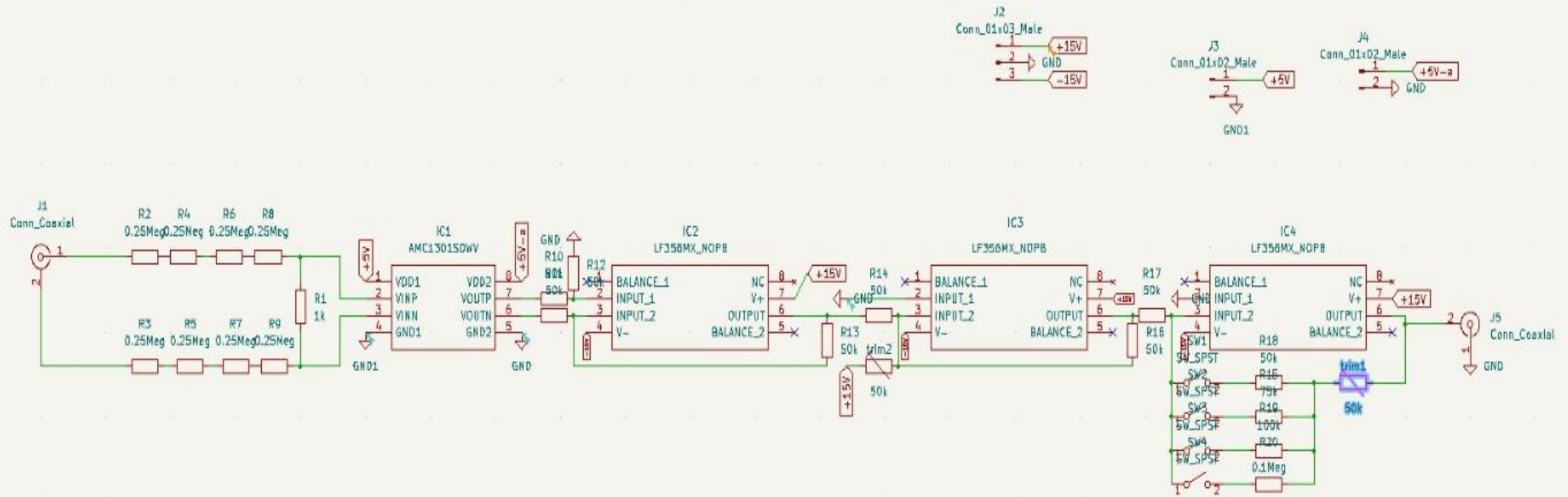
Output after differential amplifier vs output after Isolated amplifier



Trimming Values Required for gain and offset correction

Frequency (Hz)	Gain (dB)	Trimming Values (Ohm)
1-1000	-48.14	51k (+75)
1000-10k	-48.14	51k (+75 to +107)
10k-50k	-48.15 - -48.71	51k(+107 to 900)
50k-63k	-48.15 - -48.71	52k (+403)
63k-80k	-48.15 - -48.71	53k (+203)
80k-100k	-48.15 - -48.71	54k (+544)
100k-126k	-49	56k (+777)
126k -158k	-49	60k (+654)
158k- 200k	-50	68k (+300)
200k-250k	-50 to -54	1M (+9k)
250k-500k	-54 to -90	6M (+57k to +542k)
500k-1M	-98 to -114	31M (+494k to 323k)

PCB schematic diagram

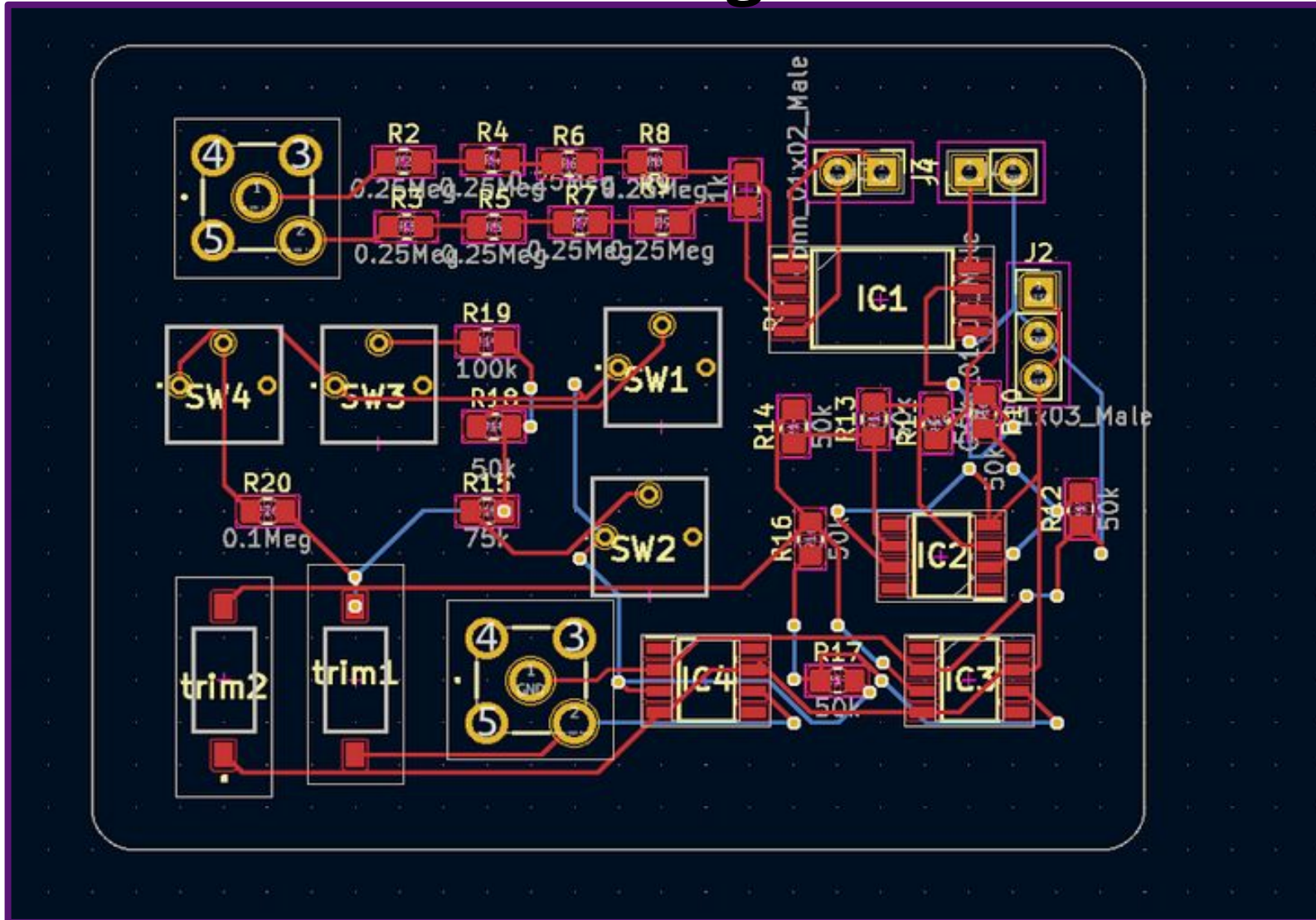


Symbol : Footprint Assignments

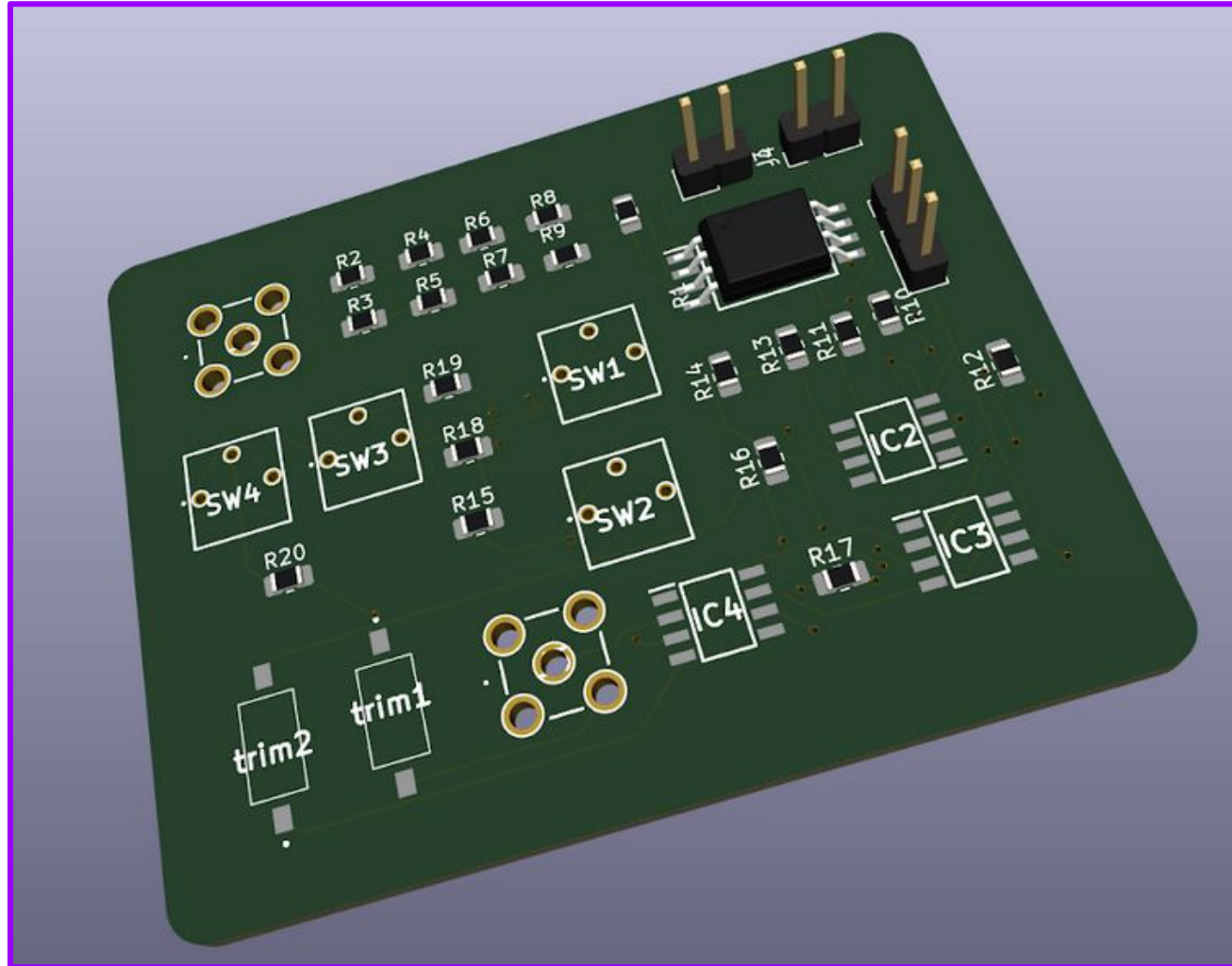
1	IC1 -	AMC1301SDWV : AMC1301SDWV:SOIC127P1150X280-8N
2	IC2 -	LF356MX_NOPB : LF356MX_NOPB:SOIC127P600X175-8N
3	IC3 -	LF356MX_NOPB : LF356MX_NOPB:SOIC127P600X175-8N
4	IC4 -	LF356MX_NOPB : LF356MX_NOPB:SOIC127P600X175-8N
5	J1 -	Conn_Coaxial : R124426123:R124426123
6	J2 -	Conn_01x03_Male : Connector_PinHeader_2.54mm:PinHeader_1x03_P2.54mm_Vertical
7	J3 -	Conn_01x02_Male : Connector_PinHeader_2.54mm:PinHeader_1x02_P2.54mm_Vertical
8	J4 -	Conn_01x02_Male : Connector_PinHeader_2.54mm:PinHeader_1x02_P2.54mm_Vertical
9	J5 -	Conn_Coaxial : R124426123:R124426123
10	R1 -	1k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
11	R2 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
12	R3 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
13	R4 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
14	R5 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
15	R6 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
16	R7 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
17	R8 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
18	R9 -	0.25Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
19	R10 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
20	R11 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
21	R12 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
22	R13 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
23	R14 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
24	R15 -	75k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
25	R16 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
26	R17 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
27	R18 -	50k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
28	R19 -	100k : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
29	R20 -	0.1Meg : Resistor_SMD:R_0805_2012Metric_Pad1.20x1.40mm_HandSolder
30	SW1 -	SW_SPST : 3362P-1-102LF:3362P_1
31	SW2 -	SW_SPST : 3362P-1-102LF:3362P_1
32	SW3 -	SW_SPST : 3362P-1-102LF:3362P_1
33	SW4 -	SW_SPST : 3362P-1-102LF:3362P_1
34	trim1 -	50k : DS04-254-2-01BK-SMT:DS04254201BKSMT
35	trim2 -	50k : DS04-254-2-01BK-SMT:DS04254201BKSMT

Footprints used in PCB Design

PCB Design



3D model of PCB Design



Future Work

Third Evaluation

Prototyping and Assembling
Integration 17/March 2023

THANK
YOU